



Material Content Data Sheet



Sales Product Name		ICE2QR0680Z		Issued		25. January 2018		
MA#		MA001043200						
Package		PG-DIP-7-4		Weight*		652.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.538	0.54	0.54	5418	5418
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5949	
wire	non noble metal	copper	7440-50-8	157.726	24.16	24.79	241568	247888
	noble metal	gold	7440-57-5	0.256	0.04	0.04	392	392
	encapsulation	organic material	carbon black	1333-86-4	1.430	0.22		2189
encapsulation	plastics	epoxy resin	-	46.223	7.08		70793	
	inorganic material	silicondioxide	60676-86-0	428.870	65.69	72.99	656844	729826
leadfinish	non noble metal	tin	7440-31-5	6.540	1.00	1.00	10017	10017
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2926	2926
glue	plastics	epoxy resin	-	0.346	0.05		530	
	noble metal	silver	7440-22-4	1.961	0.30	0.35	3003	3533
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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